

A cross-sectional view of a multi-layer printed circuit board (PCB). The diagram shows several layers of material, with internal layers labeled '8' and '1'. The board is shown with various components and features, including a central rectangular area with vertical lines, and a top section with two rectangular components. The board is shown with a complex, multi-layered structure, with various layers and components visible.

1	White	5	Grey
2	Brown	6	Pink
3	Green	7	Blue
4	Yellow	8	Red

Data and Power Interface	Gigabit Ethernet	Transfer Rate	1000 Mb/s/sec
	Fast Ethernet	Transfer Rate	100 Mb/s/sec
	Connector:	8P8C Modular Jack (RJ45), screw lock type	
	Assignment:	1 - MX1+	2 - MX1-
		3 - MX2+	4 - MX3+
		5 - MX3-	6 - MX2-
		7 - MX4+	8 - MX4-

Assignment:

1 - GPIO (Line2)	2 - Power Vcc
3 - IN1 (Line0)	4 - GND IN1
5 - Power VCC OUT	6 - OUT1 (Line3)
7 - GND (Power, GPIO)	8 - GPIO (Line1)

Lens Mount	C-Mount
Optical Filter	IR cut filter

Housing	Zinc die casting, baked varnish (until 02-2020 nickel-chrome-plated)
Protection Class	IP40 (with mounted lens and GigE cable)
Weight	120 g

Storage Temperature	-10 °C ... + 70 °C
Operating Temperature)	0 °C ... +65 °C @ T = Measurement Point or 0 °C ... +75 °C @ internal Temperature Sensor Ambient temperature above 32 °C requires heat dissipation measures.
Int. Temperature Sensor	yes, accuracy: ±2 °C (typ) -40 °C ... 0 °C ±1 °C (typ) 0 °C ... +85 °C
Humidity	10 % ... 90 % non-condensing

LED	LED 1	Green static	Link ON
		Green flash	RX active
	LED 2	Yellow static	Error
		Yellow flash	TX active